

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3865294

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HENKEL US IP LLC	02/27/2015
RECEIVING PARTY DATA	
Name:	HENKEL IP & HOLDING GMBH
Street Address:	HENKELSTRASSE 67
City:	DUESSELDORF
State/Country:	GERMANY
Postal Code:	40589
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15010531
CORRESPONDENCE DATA	
Fax Number:	(860)571-5028
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	8605715071
Email:	tricia.smith@henkel.com
Correspondent Name:	HENKEL CORPORATION
Address Line 1:	ONE HENKEL WAY
Address Line 4:	ROCKY HILL, CONNECTICUT 06067
ATTORNEY DOCKET NUMBER:	PT031607
NAME OF SUBMITTER:	STEVEN C. BAUMAN
SIGNATURE:	/Steven C. Bauman/
DATE SIGNED:	05/10/2016
Total Attachments: 3	
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source=PT031607_executedassignment_USIP_IPGMBH#page3.tif	

CONFIRMATORY ASSIGNMENT – UNITED STATES OF AMERICA

WHEREAS,

HENKEL US IP LLC of One Henkel Way, Rocky Hill, CT, 06067, United States of America; (the "Assignor"),

was the owner of inventions in the United States of America set forth and described in the attached Exhibit and forming a part of this document (the "Inventions")

AND WHEREAS,

HENKEL IP & HOLDING GMBH of Henkelstraße 67, 40589 Düsseldorf, Germany (the "Assignee"),

had acquired the entire right, title, interest, property and benefit in and for the United States of America, in and to the Inventions held by the Assignor;

NOW THEREFORE, for good and valuable consideration already provided, the receipt and sufficiency of which are hereby acknowledged,

the Assignor confirms by these presents that the Assignor had assigned, transferred and set over to the Assignee, and to the Assignee's successors, assigns, nominees or other legal representatives, its entire right, title, interest, property and benefit including any right to sue for past infringements in and for the United States of America, in and to the Inventions, any and all applications filed therefor, including any and all corresponding applications whether in the form of divisions, continuations, re-examinations, re-issues and extensions thereof, any and all patents that may issue, be granted or result therefrom for the Inventions, and any and all rights of priority resulting from the filing of any of the above-identified applications and any previously filed applications in respect of the Inventions under international conventions, treaties or otherwise, the same to be held and enjoyed as fully and exclusively as the same would have been held and enjoyed by the Assignor had this assignment not been made;

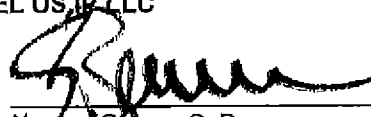
the Assignor agrees to do all lawful acts and to execute and deliver, without further consideration, all further documents as may reasonably be required by the Assignee, or by its successors, assigns, nominees, or other legal representatives, to obtain said patents in the United States of America for the Inventions and vests or secures the same in the Assignee, and in the Assignee's successors, assigns, nominees or other legal representatives; and

the Assignor grants to said Assignee, its successors, assigns, nominees or other legal representatives, agents, the power to insert on this Confirmatory Assignment any further information which may be necessary or desirable in order to legally record this document.

THIS CONFIRMATORY ASSIGNMENT may be executed in counterparts, all of which shall be considered one and the same agreement, and is binding on the heirs, executors, successors and administrators of the Assignor.

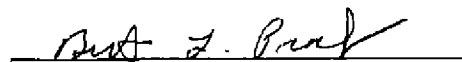
HENKEL US, IP, LLC

By


Name: Steven C. Bauman

Title: Senior Patent Counsel

Subscribed and sworn
before me this 27th day
of February, 2015

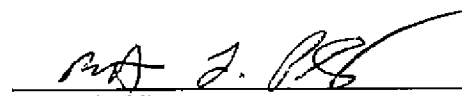

Notary Public

Date:

Feb 27, 2015

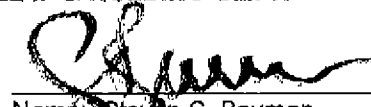
BETTY L. PROULX
NOTARY PUBLIC
MY COMMISSION EXPIRES _____

Subscribed and sworn
before me this 27th day
of February, 2015


Notary Public

HENKEL IP & HOLDING GMBH

By


Name: Steven C. Bauman

Title: Senior Patent Counsel

Date:

Feb 27, 2015

BETTY L. PROULX
NOTARY PUBLIC
MY COMMISSION EXPIRES _____

	A	B	C	E	F	G	H	I
1	Case Reference	Original Ref	CTY	Filing Date	Appl No.	Grant Date	Grant No.	Internal Title
116	PT031607		US	30-Sep-2013	61/884844			Conductive Die Attach Film for Large Die Semiconductor Packages and Compositions Useful for the Preparation Thereof
117	PT031607		TW	18-Jul-2014	103125744			Conductive Die Attach Film for Large Die Semiconductor Packages and Compositions Useful for the Preparation Thereof
118	PT031607		WO	29-Sep-2014	PCT/US2014/058000			Conductive Die Attach Film for Large Die Semiconductor Packages and Compositions Useful for the Preparation Thereof
119	PT031610		WO	29-Jan-2015	PCT/CN2015/076079			Use of Heat Curable Underfill Adhesives And Its Application Method
120	PT031610		TW	29-Jan-2015	103102329			Use of Heat Curable Underfill Adhesives And Its Application Method
121	PT031617		TW	12-Mar-2014	103100000			Examine-Containing Composites And Compositions Thereof
122	PT031617		WO	18-Mar-2014	PCT/US2014/027150			Examine-Containing Composites And Compositions Thereof
123	PT031640		TW	23-Jan-2014	103102329			Flexible Conductive Ink
124	PT031649		WO	22-Oct-2015	PCT/US2015/066869			Adhesive Composition
125	PT031649		TW	25-Oct-2015	103139750			Adhesive Composition
126	PT031601		TW	10-Mar-2014	103110177			Dienylbenzophenone Coupled and Thermosetting Resin Compositions Having Retardability
127	PT031661		WO	21-Mar-2014	PCT/US2014/091439			Dienylbenzophenone Coupled and Thermosetting Resin Compositions Having Retardability
128	PT031601		WO	20-May-2014	PCT/US2014/059095			Printer Compositions for Injection Molding
129	PT031793		US	15-Dec-2014	14/578868			Photocurable Dielectric Block Copolymers For Heat Treat Adhesives
130	PT031644		WO	22-May-2014	PCT/US2014/099450			Tri-Layer Adhesive For The Encapsulation of Electronic Devices
131	PT031644		TW	29-May-2014	103140199			Tri-Layer Adhesive For The Encapsulation of Electronic Devices

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